



Product Change Notification / SYST-14BZTB577

Date:

26-Feb-2024

Product Category:

Wireless IC, Wireless Modules

PCN Type:

Document Change

Notification Subject:

Data Sheet - PIC32MZ1025W104 MCU and WFI32E01 Family Data Sheet

Affected CPNs:

[SYST-14BZTB577_Affected_CPN_02262024.pdf](#)

[SYST-14BZTB577_Affected_CPN_02262024.csv](#)

Notification Text:

SYST-14BZTB577

Microchip has released a new Datasheet for the PIC32MZ1025W104 MCU and WFI32E01 Family Data Sheet of devices. If you are using one of these devices please read the document located at [PIC32MZ1025W104 MCU and WFI32E01 Family Data Sheet](#).

Notification Status: Final

Description of Change:

Document

- Updated document title to PIC32MZ W1 MCU and WFI32 Module with Wi-Fi® and Hardware-Based Security Accelerator Data Sheet.
- All the information related to the WFI32E02 Module in this data sheet is Preliminary Information.

“Introduction”

- Added WFI32E02 Module variant. “WFI32 Module Features”
- Added WFI32E02 Module variant.
- Added features related to WFI32E02 Module variant.
- Table 1 and Table 2 updated with WFI32E02 Module variant.
- Table 3 updated with EPAD pin information for the PIC32MZ1025W104 SOC.

1.2 “WFI32 Module Ordering Information”

- Updated title to WFI32 Module Ordering Information.

- Table 1-2 updated with WFI32E02 Module variant ordering information.
- Updated Figure 1-2. 2.2 “Function-wise Pinout Description”
- Added function-wise pinout details for the WFI32E02 Module variant.

3.0 “WFI32 Module Description”

- Updated title to WFI32 Module Description.
- Added WFI32E02 Module variant.
- Updated Figure 3-1 by adding I2C2 peripheral text information near the Trust & Go block.
- Added Figure 3-2 for WFI32E02 Module variant.

3.1.1 “WFI32E01 Pinout details”

- Updated Figure 3-3 with test points.

3.1.2 “WFI32E02 Module Pinout Details”

- Added Figure 3-4 for WFI32E02 Module pinout.
- Added Table 3-2 for WFI32E02 Module pin description.

3.2 “Basic Connection Requirement”

- Updated Figure 3-5.
- Added Figure 3-6 for WFI32E02 Module basic connections.

3.2.1 “Power Pins”

- Added Figure 3-8. 3.2.5 “Unused I/O pins”
- Updated section to include the usage of unused pins in Low Power modes.

3.3 “WFI32 Module Placement Guidelines”

- Updated title to WFI32 Module Placement Guidelines.
- Added Figure 3-11 for Module placement recommendations.
- Added Figure 3-15

3.4 “WFI32 Module Routing Guidelines”

- Added Figure 3-18.
- Updated Figure 3-19 by removing module pad pin text.

14.0 “Peripheral Trigger Generator (PTG)”

- Added Note 4 for bit “10” of “PTGSWT: Software Trigger bit”.
- Updated Note 2 for bit “7” of “PTGSTRT: Start PTG Sequencer bit”.

20.0 “Output Compare”

- Updated Table 20-1 by swapping X(MSB) Clock/Data and Y(MSB) Clock/Data columns.

22.0 “Serial Quad Interface (SQI)”

- Updated Note 1 of FIGURE 22-1: “SQI Module Block Diagram” to include the information about configuration of CFGCON3.SPILLPOSTDIV2.

24.0 “UART”

- Updated Introduction with the information regarding the usage of CFGCON1.HSUARTEN bit to enable the UART1 on PPS pins.
- Added Note for bit “3” of Register 24-1: “UxMODE: UARTx Mode Register”.

31.0 “Controller Area Network-Flexible Data-Rate (CAN-FD) Module”

- Updated bit “7” description of Register 31-1: “CFD2CON: CAN Control Register”
- Added Note for bit “7” of Register 31-1: “CFD2CON: CAN Control Register”.

41.1.1 “DC Characteristics”

- Updated Table 41-10, WSM current to 2.7 mA and WDS current to 1.2 mA.

41.1.2 “AC Characteristics and Timing Parameters”

- Updated Table 41-30 with latest supported clock frequency and related parameters.

41.2 “WFI32 Module Electrical Specifications”

- Updated Table 41-44 with AVDD parameters.

42.2 “WFI32E02 Module Packaging Information”

- Added section

42.2.1.2 “WFI32E02 Module Package Marking” for module package marking information.

- Added section

42.2.2.2 “WFI32E02 Module Packaging Dimension” for module packing dimension.

- Added section

42.2.3.2 “WFI32E02 Module Recommended Footprint” for module recommended footprint.

42.2.1 “Module Package Marking”

- Updated the section with latest package marking information. Appendix A: “Regulatory Approvals”
- Updated with WFI32E02 Module variant regulatory information. Appendix B: “Alternate Module Placement Guidelines”
- Added for alternate module placement recommendation.

Impacts to Data Sheet: See above details.

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 26 Feb 2024

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachments:

[PIC32MZ1025W104 MCU and WFI32E01 Family Data Sheet](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

PIC32MZ1025W104132-I/NX

WFI32E01PC-I

WFI32E01PCI

WFI32E01PE-I

WFI32E01UC-I

WFI32E01UCI

WFI32E01UE-I

WFI32E02UC-I

WFI32E02UCI

WFI32E02UE